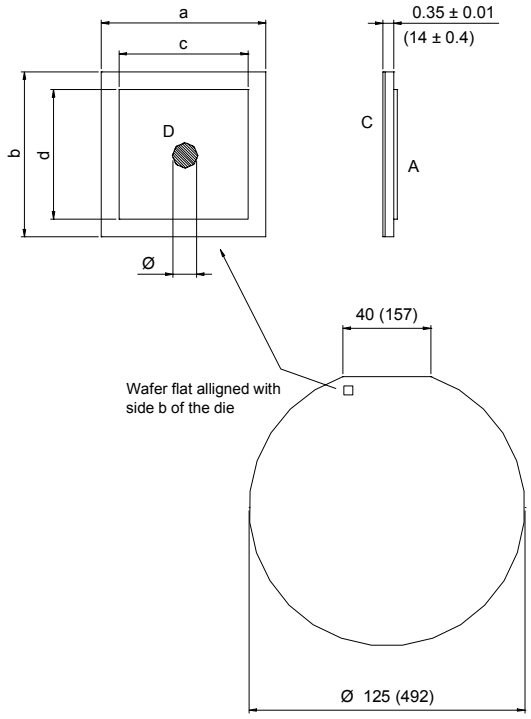
International
IOR Rectifier

SC060.....5. Series

SCHOTTKY DIE 060 x 060 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
   a = 1.52 + 0, - 0.01
   (60 + 0, - 0.4)
   b = 1.52 + 0, - 0.01
   (60 + 0, - 0.4)
   c = 1.37 + 0, - 0.01
   (54 + 0, - 0.4)
   d = 1.37 + 0, - 0.01
   (54 + 0, - 0.4)
   Ø = 0.7 ± 0.1
   (30 ± 4)
4. LETTER DESIGNATION:
   A = Anode (Top Metal)
   C = Cathode (Back Metal)
   D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
   Recommended Blade
   SEMITEC S1025 QS00 Blade
   Sawing Street
   0.05 + 0, - 0.005
   (2 + 0, - 0.2)

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T_J Max. (°C)	V_R (V)	Typ. I_R @ 25°C (µA)	Typ. I_R @ 125°C (mA)	Max. V_F @ I_F (V)	Package Style
SC060**R**015x5x	125	15	800	50	0.35 @ 3A	SMC
SC060**S**020x5x	150	20	n.a. contact factory			
SC060**S**030x5x	150	30	40	15	0.45 @ 3A	DPAK (TO-252)
SC060**S**045x5x	150	45	30	13	0.53 @ 3A	DPAK (TO-252)
SC060**S**060x5x	150	60	25	12	0.61 @ 3A	DPAK (TO-252)
SC060**H**045x5x	175	45	n.a. contact factory			
SC060**H**100x5x	175	100	2.5	1.5	0.81 @ 3A	DPAK (TO-252)
SC060**H**150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC060xxxx**A**5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC060xxxx**S**5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.
Shelf life for parts stored in above condition is 2 years.
If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC060xxxxx5**B**	Inked Probed Unsawn Wafer (Wafer in Box)	4600
SC060xxxxx5**R**	Probed Die in Tape & Reel	n. a.
SC060xxxxx5**P**	Probed Die in Waffle Pack	n.a.
SC060xxxxx5**F**	Inked Probed Sawn Wafer on Film	4600

Ordering Information Table

Device Code

SC	060	S	060	A	5	B
1	2	3	4	5	6	7

1 - Schottky Die

2 - Chip Dimension in Mils

3 - Process (see Electrical Characteristics Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

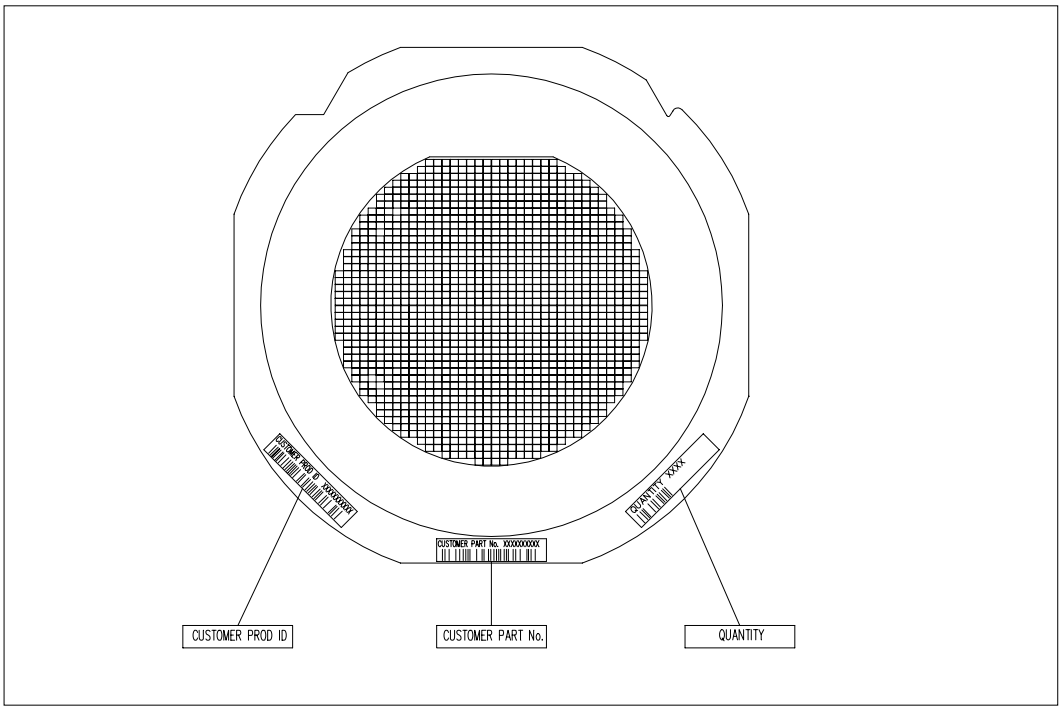
4 - Voltage code: Code = V_{RRM}

5 - Chip surface metallization (see Mechanical Data Table)

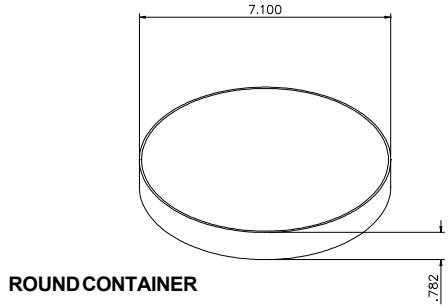
6 - Wafer Diameter in inches

7 - Packaging (see Packaging Table)

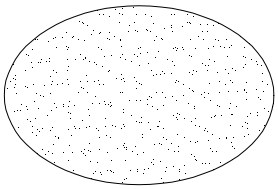
Wafer on Film



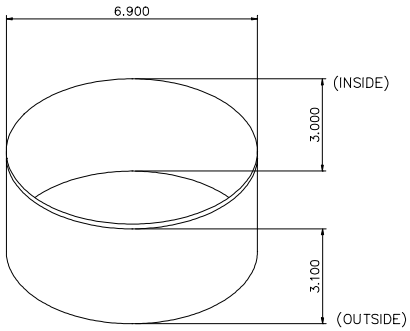
Wafer in Box

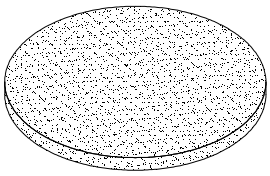


ROUND CONTAINER



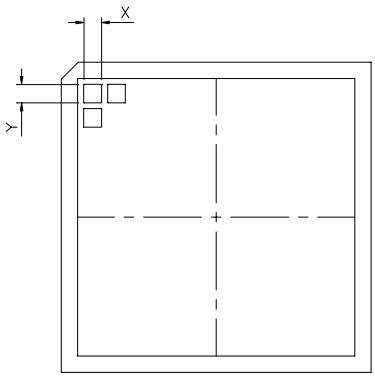
TYVEK DISK

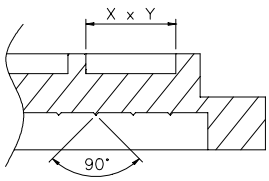




FOAM DISK

Die in Waffle Pack





CHIP TRAY POCKET

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IOR Rectifier

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